

650V Super-Junction Power MOSFET

FEATURES

- Very low FOM $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant

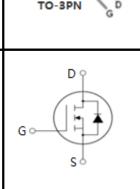
APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

TO-220 GDS	TO-220F GDS	TO-BPN GD S
		Dγ

RoHS

Device Marking and Package Information					
Device	Package	Marking			
TPP65R160C	TO-220	65R160C			
TPA65R160C	TO-220F	65R160C			
TPV65R160C	TO-3PN	65R160C			



Absolute Maximum Ratings $T_c = 25^{\circ}C$, unless otherwise noted					
Deservation	Cumhal	Value			l la lí
Parameter	Symbol	TO-220	TO-3PN	TO-220F	Unit
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}		650		V
Continuous Drain Current	I _D	20			А
Pulsed Drain Current (note1)	I _{DM}	60			А
Gate-Source Voltage	V _{GSS}	±30		V	
Single Pulse Avalanche Energy (note2)	E _{AS}	480		mJ	
Avalanche Current (note1)	I _{AR}	4		А	
Repetitive Avalanche Energy (note1)	E _{AR}	0.75		mJ	
Power Dissipation ($T_c = 25^{\circ}C$)	Dissipation ($T_c = 25^{\circ}C$) P_D 151			34	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150			°C

Thermal Resistance						
Desembles	Cumb al	Value			11	
Parameter	Symbol	TO-220	TO-3PN	TO-220F	Unit	
Thermal Resistance, Junction-to-Case	R _{thJC}	0.83		3.7	00.00	
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62		80	°C/W	

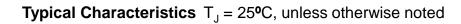


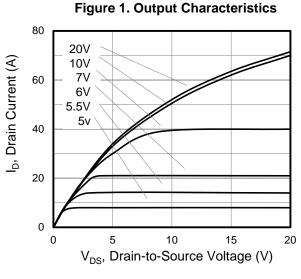
		Value				
Parameter	Symbol Test Conditions -		Min.	Тур.	Max.	Unit
Static		• • •				
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_{D} = 250 \mu A$	650			V
Zeus Cata Valtaria Drain Currant	I _{DSS}	$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	
Zero Gate Voltage Drain Current		V _{DS} = 650V, V _{GS} = 0V, T _J = 150°C			100	μA
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 30 V$			±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5		4.0	V
Drain-Source On-Resistance (Note3)	$R_{DS(on)}$	V _{GS} = 10V, I _D = 10A		0.14	0.16	Ω
Forward Transconductance (Note3)	g _{fs}	V _{DS} = 10V, I _D = 10A		18.8		S
Dynamic		•				
Input Capacitance	C _{iss}			2328		
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 50V,$		116		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		7		
Total Gate Charge	Q _g			46		nC
Gate-Source Charge	Q _{gs}	$V_{DD} = 520V, I_D = 20A, V_{GS} = 10V$		11		
Gate-Drain Charge	Q_{gd}			13		
Turn-on Delay Time	t _{d(on)}			43		
Turn-on Rise Time	t _r	V _{DD} = 400V, I _D = 20A,		14		
Turn-off Delay Time	t _{d(off)}	$R_{\rm G} = 25\Omega$		150		ns
Turn-off Fall Time	t _f			7		
Drain-Source Body Diode Characteris	stics	· · ·				
Continuous Body Diode Current	I _S	T 0500			20.6	۸
Pulsed Diode Forward Current	I _{SM}	T _C = 25°C			70	A
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}C, I_{SD} = 20A, V_{GS} = 0V$		0.95	1.2	V
Reverse Recovery Time	t _{rr}			460		ns
Reverse Recovery Charge	Q _{rr}	$V_R = 520V, I_F = I_S,$ $di_F/dt = 100A/\mu s$		8.2		μC
Peak Reverse Recovery Current	l _{rrm}			35		А

Notes

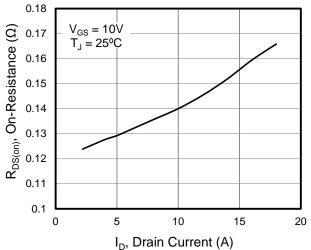
- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. $I_{AS} = 4A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^{\circ}C$
- 3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 1%

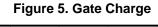


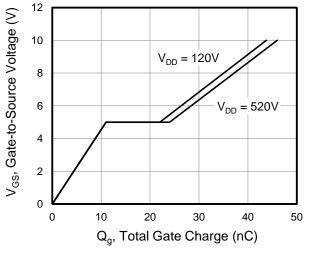


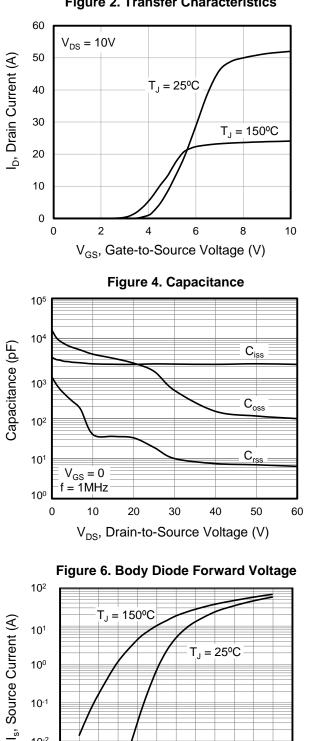












0.8

V_{SD}, Source-to-Drain Voltage (V)

1

1.2

1.4

10-1

10-2

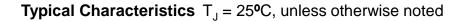
10⁻³

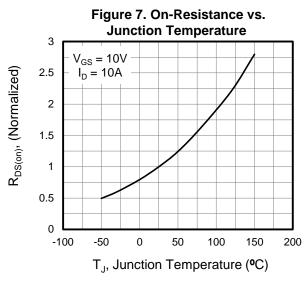
0.2

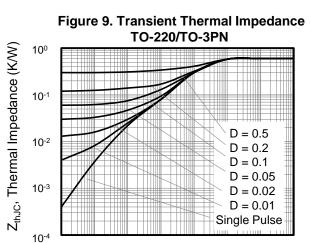
0.4

0.6









10-4

T_p, Pulse Width (s)

10-3

10-2

10-1

10⁰

10-7

10⁻⁶

10-5

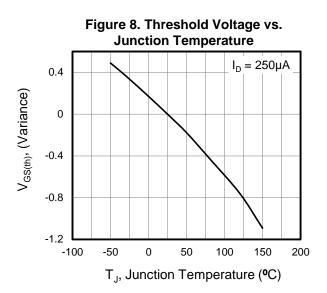
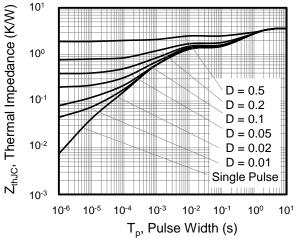
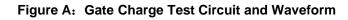


Figure 10. Transient Thermal Impedance TO-220F







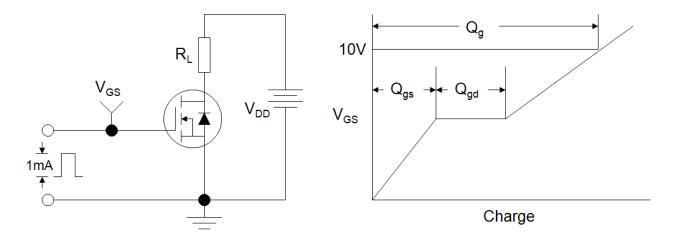


Figure B: Resistive Switching Test Circuit and Waveform

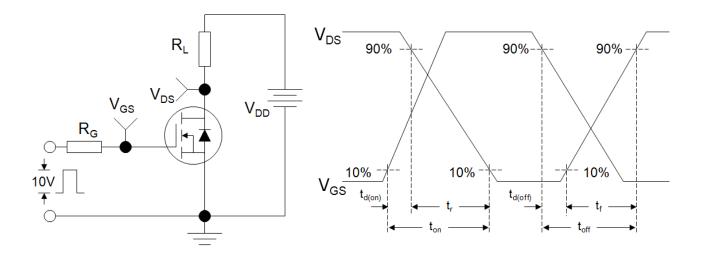
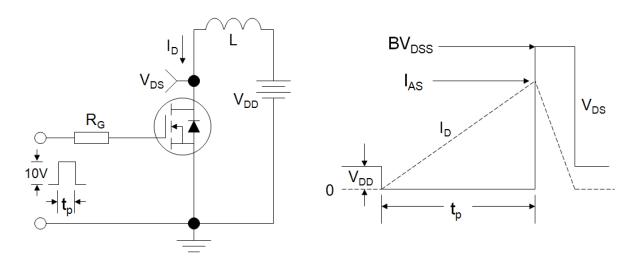


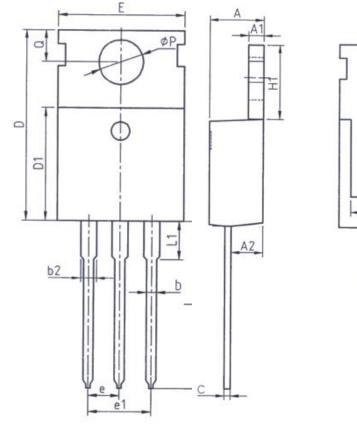
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

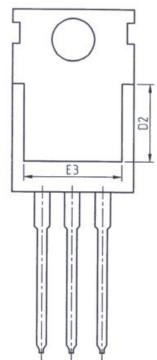


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TO-220



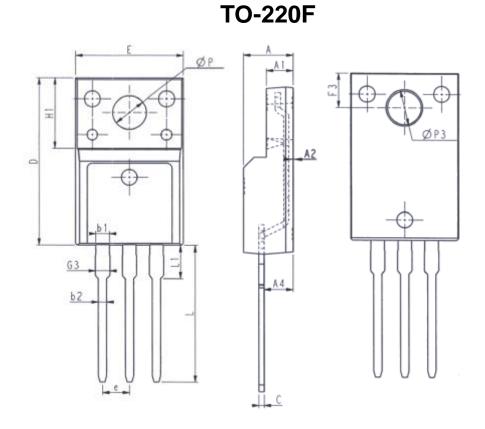


Unit: mm				
Symbol	Min.	Max.		
Α	4.37	4.77		
A1	1.25	1.45		
A2	2.20	2.60		
b	0.70	0.95		
b2	1.17	1.47		
С	0.40	0.65		
D	15.10	16. 10		
D1	8.80	9.40		
D2	5.50	-		

Unit: mm				
Symbol	Min.	Max.		
E	9.70	10. 30		
E3	7.00	-		
e	2.54BSC			
e1	5. 08BSC			
H1	6. 25	6.85		
L	12.75	13.80		
L1	-	3. 40		
Р	3. 40	3.80		
Q	2.60	3.00		

E

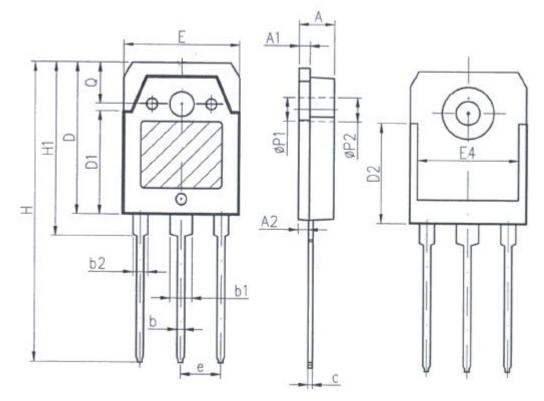
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Unit: mm			Unit: mm			
Symbol	Min.	Max.	Symbol	Min.	Max.	
E	9.96	10.36	L	12. 68	13. 28	
Α	4.50	4.90	L1	2.93	3.13	
A1	2.34	2.74	Р	3.03	3. 38	
A2	0.30	0.60	P3	3.15	3.65	
A4	2.56	2.96	F3	3. 15	3.45	
с	0.40	0.65	G3	1.25	1.55	
D	15. 57	16. 17	b1	1.18	1.43	
H1	6. 70REF		b2	0.70	0.95	
е	2. 54BSC					



TO-3PN



Unit:mm				
Symbol	Min.	Max.		
Α	4.6	5		
A1	1.4	1.65		
A2	1.18	1. 58		
b	0.8	1.2		
b1	2.8	3.2		
b2	1.8	2.2		
c	0.5	0.75		
D	19.6	20.2		
D1	13. 55	14. 25		
D2	12. 9	PREF		
E	15.35	15.85		
E4	12.6	-		
e	5. 45TYP			
Н	40.1	40.9		
H1	23.15	23.65		
P1	3. 2REF			
P2	3. 5REF			



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